

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Robert F. Wallace  
Assignee: SanDisk Corporation  
Title: Semiconductor Package Using Terminals Formed on a  
Conductive Layer of a Circuit Board  
Serial No.: Unassigned Filed: May 24, 2001  
Examiner: Unknown Group Art Unit: Unknown  
Docket No.: M-10238-2C US

San Francisco, California  
May 24, 2001

BOX PATENT APPLICATION  
ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D. C. 20231

**PRELIMINARY AMENDMENT**

Dear Sir:

Please amend the above-identified continuation patent application as follows:

IN THE SPECIFICATION

Please amend the specification by inserting on Page 1, line 4, before "Field of the  
Invention" the following heading and added paragraph:

--CROSS-REFERENCE TO RELATED APPLICATIONS

This is a continuation of U.S. Application Serial No. 09/487,106, filed January  
19, 2000, <sup>now US Patent 6410355</sup> entitled "Semiconductor Package Using Terminals Formed on a Conductive  
Layer of a Circuit Board" by Robert F. Wallace which is a divisional of U.S.

Application Serial No. 09/906,140 filed on June 11, 1998, now U.S. Patent No.